| ABBOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES®<br>Material Comp<br>© Copyright 2005. 1<br>international and Pau | PC, Bannockl   | ourn, Illinois. A | Il rights reserved untions. | under both              | This docume<br>level parts, t | ent is a decla<br>the declaratio                                | ration of<br>on encom | the substance<br>passes all lov | es withir<br>ver level          | the manufactur<br>materials for w | rer listed i<br>hich the n | tem. Not<br>nanufactu | e: if the it<br>arer has er | em is an assongtion of the second sec | embly with lowe<br>sponsibility. |
|--|--|-------------------|-----------------------------|-------------------------|-------------------------------|---|-----------------------|---------------------------------|---------------------------------|-----------------------------------|----------------------------|-----------------------|-----------------------------|--|----------------------------------|
|  | IPC Web Site for Information on IPC-1752 Standard Form Typ<br>http://www.ipc.org/IPC-175x Distribute |                   |                             |                         | e *                           | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Mater |                       |                                 |                                 |                                   | als and Mfg Information    |                       |                             |  |                                  |
| Supplier Information   |  |                   |                             |                         |                               |   |                       |                                 |                                 |                                   |                            |                       |                             |  |                                  |
| Company name*  | Company un   | Company unique ID |                             |                         | Unique ID Authority           |   |                       |                                 |                                 | Response Date*                    |                            |                       |                             |  |                                  |
| onsemi   |  |                   |                             |                         |                               |   |                       |                                 |                                 | 2023-06                           | 2023-06-08                 |                       |                             |  |                                  |
| Contact Name   | Title - Conta  | Title - Contact   |                             |                         | Phone - Contact*              |   |                       |                                 |                                 | Email - Contact*                  |                            |                       |                             |  |                                  |
| Product-Env-Stewards   | Product Enviro Compliance  |                   |                             |                         | NA                            |   |                       |                                 |                                 | Product-Env-Stewards@onsemi.com   |                            |                       |                             |  |                                  |
| Authorized Representative*   | Title - Representative   |                   |                             | Phone - Representative* |                               |   |                       | Email - Representative*         |                                 |                                   |                            |                       |                             |  |                                  |
| Product-Env-Stewards   | Product Enviro Compliance  |                   |                             |                         | NA                            |   |                       |                                 | Product-Env-Stewards@onsemi.com |                                   |                            |                       |                             |  |                                  |
| Requester Item Number  | Mfr Item Numb  |                   | Number Mfr Item Name        |                         |                               | Effective D   | ate Vei               | te Version Manufacturing Site   |                                 | acturing Site                     | ,                          | Weight*               | U                           | JOM  | Unit Type                        |
|  | NCV301   | 2DTBR2G           | PWM CONTROLLER              |                         |                               | 2023-06-08 PH1  |                       |                                 | 45.24                           |                                   | n                          | ng                    | Each                        |  |                                  |
| Manufacturing Proccess Informa   | tion   |                   |                             |                         |                               |   |                       |                                 |                                 |                                   |                            |                       | ł                           |  |                                  |
| Terminal Plating / Grid Array Ma   | aterial  | Terminal Base     | Alloy                       | J-STD-020 MSL Rating    |                               | Peak Process Body Te  |                       | ody Temperat                    | perature Max Time at Peak       |                                   | Temperat                   | Temperature Number of |                             | Reflow Cycle   | es                               |
| Precious metal (e.g. Ag,Au, NiPdAu) (no<br>Sn)   |  | CU Alloy 3        |                             | 3                       |                               | 260   |                       | С                               | 30                              | 30                                |                            | ds 3                  |                             |  |                                  |
| Comments   |  |                   |                             |                         |                               |   |                       |                                 |                                 |                                   |                            |                       |                             |  |                                  |
| TTENTION: MSL 3 Rated item require   | s Bake and I   | Dry Pack (after   | electrical test)            |                         |                               |   |                       |                                 |                                 |                                   |                            |                       |                             |  |                                  |
| or more information regarding material   | composition  | please refer to   | page 3                      |                         |                               |   |                       |                                 |                                 |                                   |                            |                       |                             |  |                                  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                  | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------------|--------|---------|-----------------|
| Die                  | 2.0    | mg              | Supplier | Silicon (Si)               | 7440-21-3        |        | 2       | mg              |
| Die Attach           | 1.44   | mg              | Supplier | Silver (Ag)                | 7440-22-4        |        | 1.08    | mg              |
|                      |        |                 | Supplier | Epoxy resins               | 129915-35-1      |        | 0.36    | mg              |
| Lead Frame           | 22.54  | mg              | Supplier | Iron (Fe)                  | 7439-89-6        |        | 0.4283  | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8        |        | 22.1117 | mg              |
| Mold Compound-Black  | 19.0   | mg              |          | Epoxy resin                | proprietary data |        | 0.95    | mg              |
|                      |        |                 | Supplier | Phenolic Resin             | Proprietary Data |        | 0.95    | mg              |
|                      |        |                 | Supplier | Ortho Cresol Novolac Resin | 29690-82-2       |        | 0.38    | mg              |
|                      |        |                 | Supplier | Carbon Black (C)           | 1333-86-4        |        | 0.095   | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0       |        | 16.625  | mg              |
| Plating              | 0.04   | mg              | Supplier | Palladium (Pd)             | 7440-05-3        |        | 0.003   | mg              |
|                      |        |                 | В        | Nickel (Ni)                | 7440-02-0        |        | 0.0364  | mg              |
|                      |        |                 | Supplier | Gold (Au)                  | 7440-57-5        |        | 0.0006  | mg              |
| Wire Bond - Au       | 0.22   | mg              | Supplier | Gold (Au)                  | 7440-57-5        |        | 0.22    | mg              |